



## Description

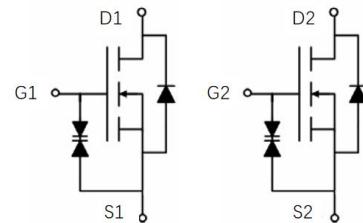
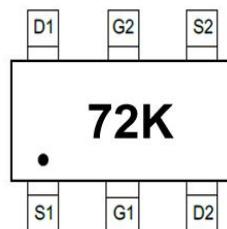
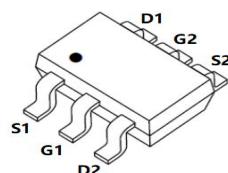
### JMT N-channel MOSFET

#### Features

- $V_{DS}=60V$ ,  $I_D=0.2A$
- $R_{DS(ON)}<2.1\Omega$  @  $V_{GS} = 10V$
- $R_{DS(ON)}<2.7\Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

#### Application

- Battery Operated Systems
- Direct logic-level Interface: TTL/CMOS
- Solid-State Relays



SOT-363-6L top view

Marking and pin Assignment

Schematic diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
72K	JMTLB2N7002KDS	TAPING	SOT-363-6L	7inch	3000	120000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	0.2	A
		$T_A = 100^\circ C$	0.13	
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		0.8	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	0.38	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		328	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

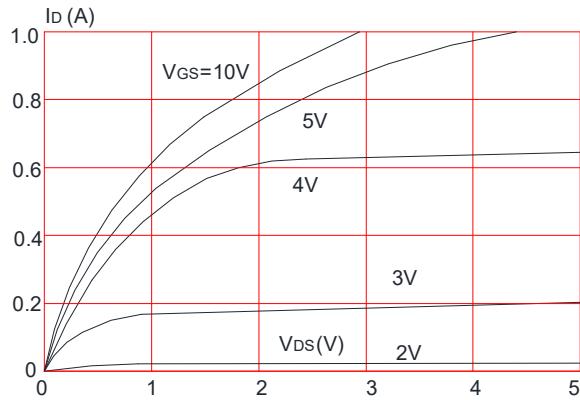
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = 10\mu\text{A}$	60	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}$ , $V_{GS} = 0\text{V}$ ,	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1	-	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = 10\text{V}$ , $I_D = 0.3\text{A}$	-	1.6	2.1	$\Omega$
		$V_{GS} = 4.5\text{V}$ , $I_D = 0.2\text{A}$	-	1.9	2.7	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1.0\text{MHz}$	-	28	-	pF
$C_{oss}$	Output Capacitance		-	11	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	4	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = 10\text{V}$ , $I_D = 0.3\text{A}$ , $V_{GS} = 4.5\text{V}$	-	1.7	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	0.6	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 10\text{V}$ , $I_D = 0.2\text{A}$ , $R_{\text{GEN}} = 10\Omega$ , $V_{GS} = 10\text{V}$	-	2	-	ns
$t_r$	Turn-on Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	7	-	ns
$t_f$	Turn-off Fall Time		-	20	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	0.2	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	0.8	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_s = 0.2\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

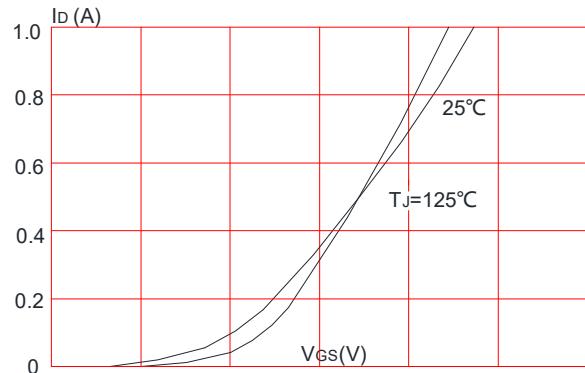
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics

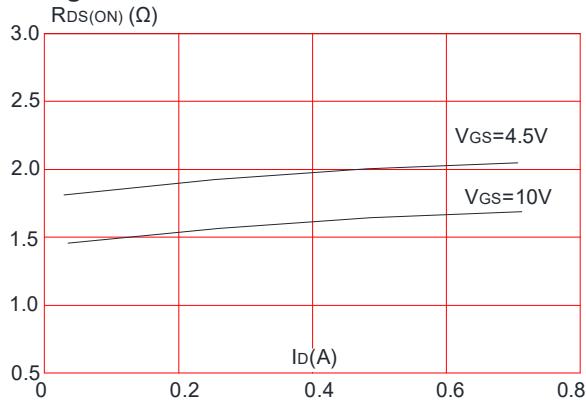
**Figure 1:** Output Characteristics



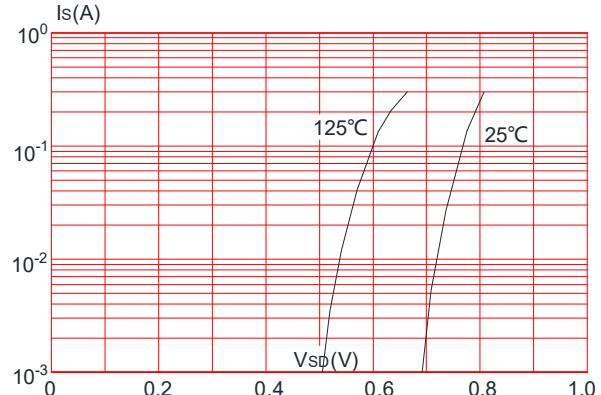
**Figure 2:** Typical Transfer Characteristics



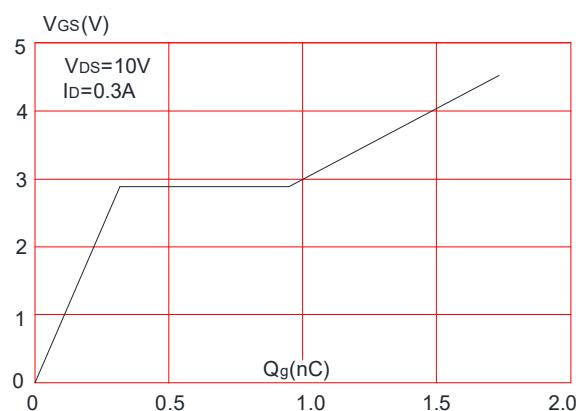
**Figure 3:** On-resistance vs. Drain Current



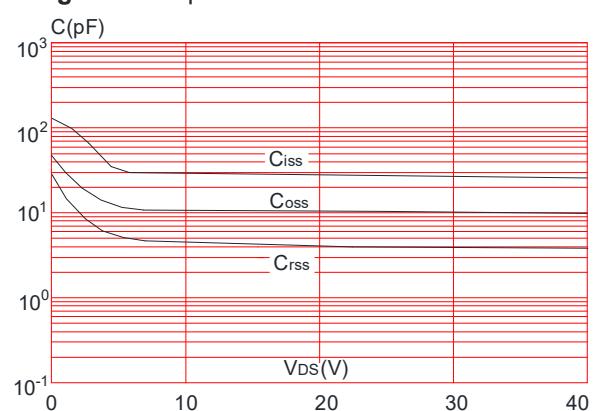
**Figure 4:** Body Diode Characteristics



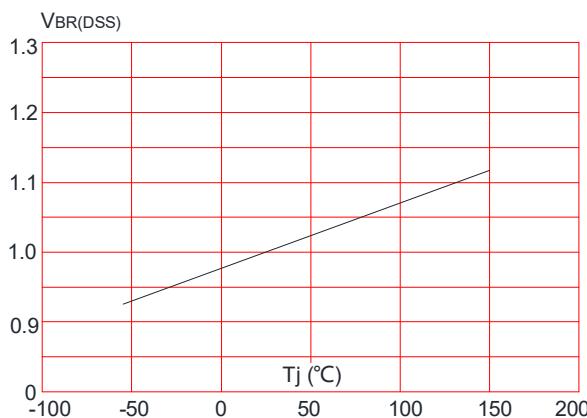
**Figure 5:** Gate Charge Characteristics



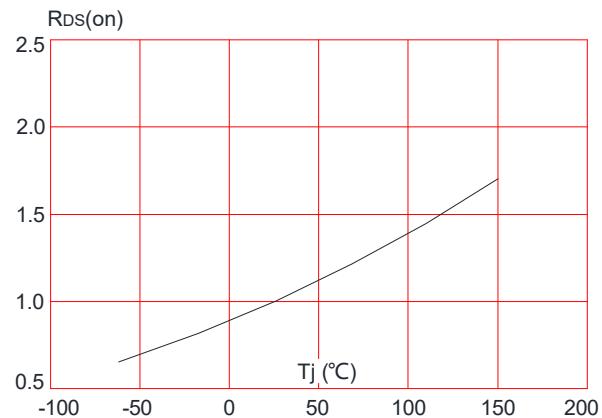
**Figure 6:** Capacitance Characteristics



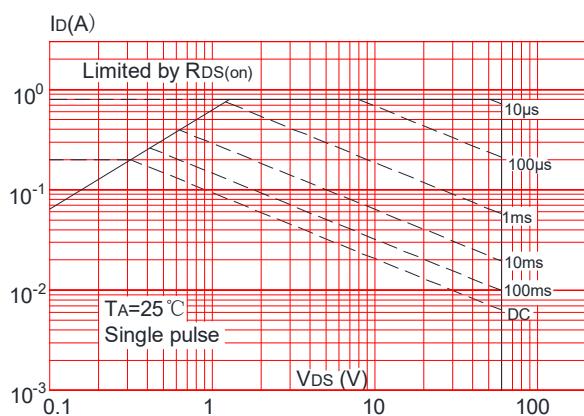
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



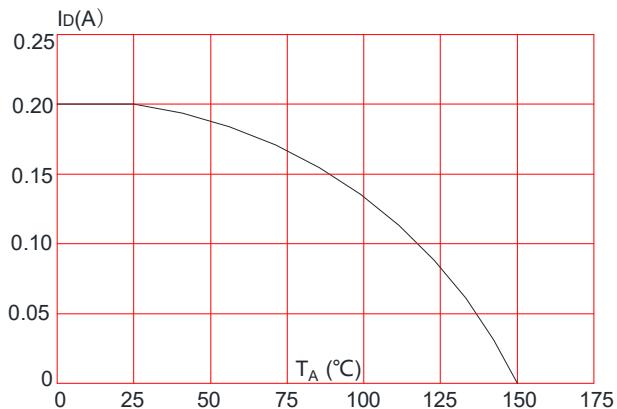
**Figure 8:** Normalized on Resistance vs. Junction Temperature



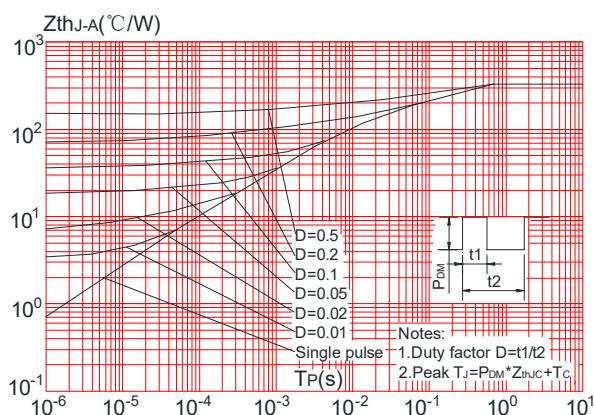
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit

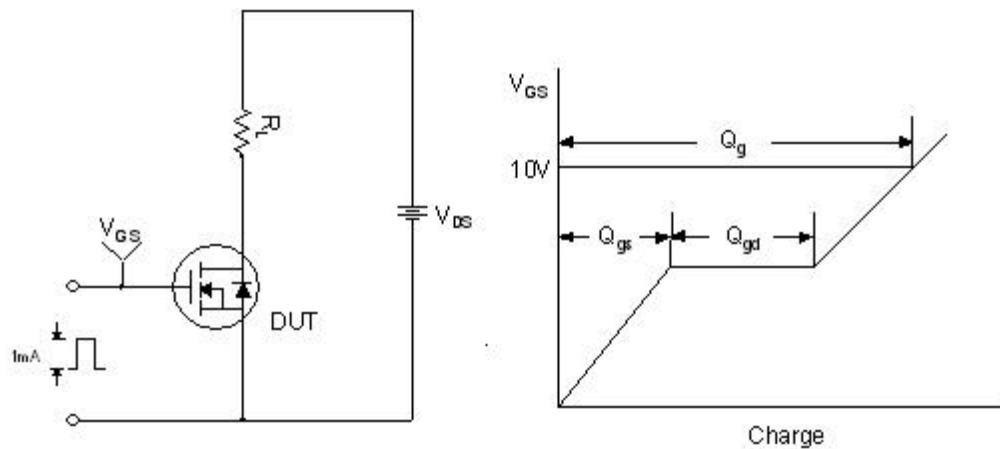


Figure 1. Gate Charge Test Circuit & Waveform

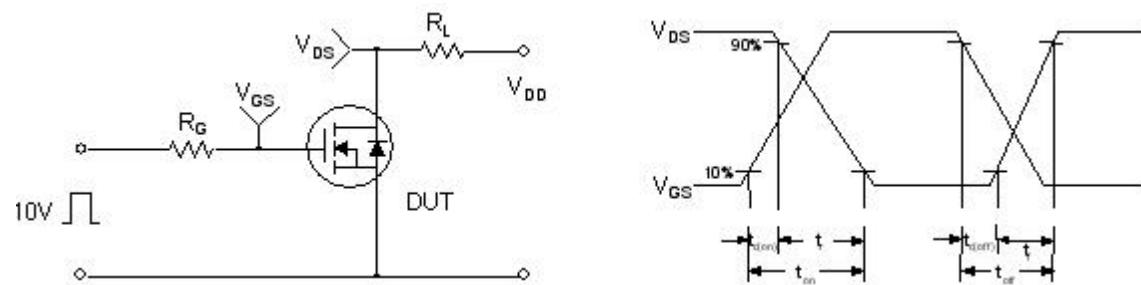


Figure 2. Resistive Switching Test Circuit & Waveforms

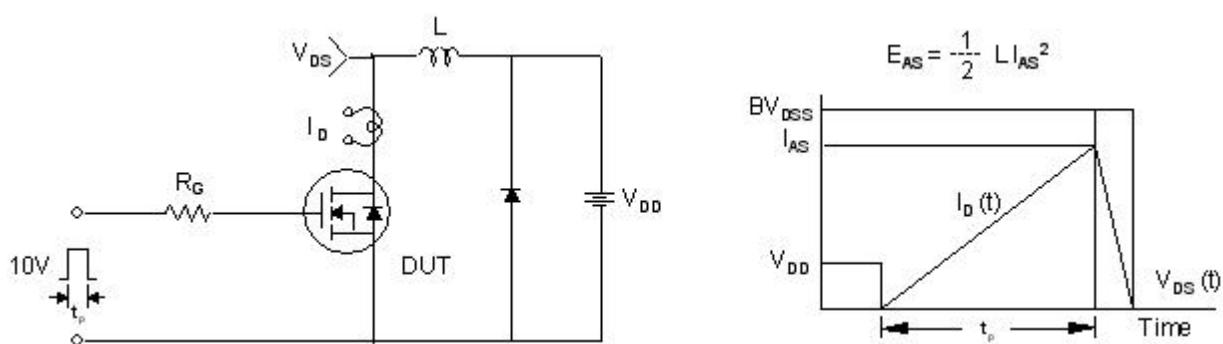
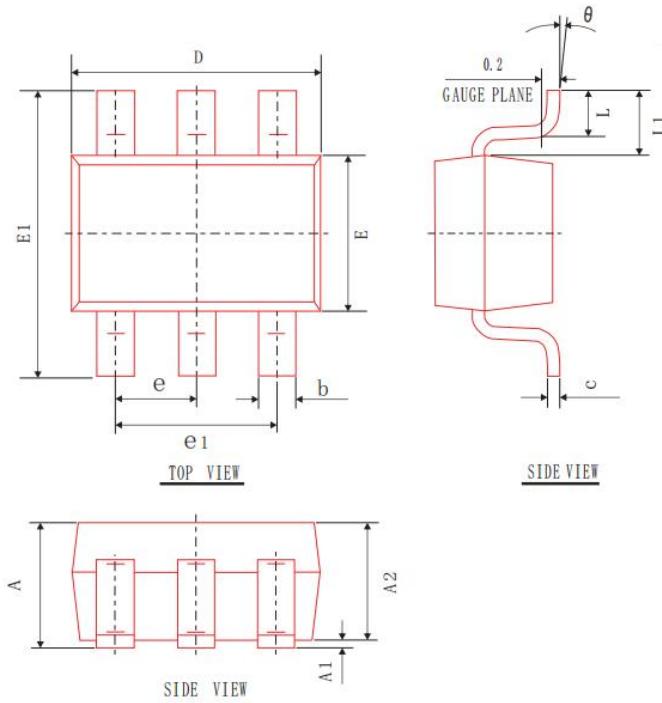


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data-SOT-363-6L

COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.90	0.95	1.00
b	0.20	0.25	0.30
c	0.08	0.10	0.15
e1	1.20	1.30	1.40
D	2.00	2.10	2.20
E	1.15	1.25	1.35
E1	2.15	2.30	2.45
L	0.26	0.36	0.46
θ	0°	4°	8°
L1		0.525 REF	
e		0.65 TYP	

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